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(54) Title: CURABLE ENCAPSULANT COMPOSITION AND METHOD FOR PREPARING IT

(57) Abstract: An encapsulant for encapsulating electronic components and a method of making and/or using the encapsulant may be provided. An electronic device that includes the encapsulant may be provided. The curable encapsulant composition may include a mixture of a functionalized polymer and at least one reactive monomer composition. The reactive monomer composition may include a reactive monomer component that may be a low temperature solid and may be present in an amount in the reactive monomer composition a range of greater than about 20 weight percent based on the total weight of reactive monomer composition. The mixture, at about low temperature, may be solid or tack-free, or both solid and tack-free.

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